

1	551	semiconductor and test\$3 and (parasitic with diode)	USPAT; US-PGPUB; 2003/06/04 EPO; JPO; 12:10 DERWENT; IBM_TDB
2	19	(semiconductor and test\$3 and (parasitic with diode)) and (257/467,48,797,B21,521.ccls. 73/777.ccls. 324/765-769,158,252.ccls. 374/178,183-185.ccls. D10/77.ccls. 438/18.ccls.) not ((semiconductor and test\$3 and heat\$3 and sensor and parasitic) and (257/467,48,797,B21,521.ccls. 73/777.ccls. 324/765-769,158,252.ccls. 374/178,183-185.ccls. D10/77.ccls. 438/18.ccls.))	USPAT; US-PGPUB; 2003/06/03 EPO; JPO; 15:38 DERWENT; IBM_TDB
3	85	semiconductor and test\$3 and (parasitic with diode) and parasitic.ab.	USPAT; US-PGPUB; 2003/06/04 EPO; JPO; 12:10 DERWENT; IBM_TDB
4	10769	257/467,48,797,B21,521.ccls. 73/777.ccls. 324/765-769,158,252.ccls. 374/178,183-185.ccls. D10/77.ccls. 438/18.ccls.	USPAT; US-PGPUB; 2004/06/14 EPO; JPO; 12:40 DERWENT; IBM_TDB
5	5	(semiconductor and test\$3 and (parasitic with diode) and parasitic.ab.) and (257/467,48,797,B21,521.ccls. 73/777.ccls. 324/765-769,158,252.ccls. 374/178,183-185.ccls. D10/77.ccls. 438/18.ccls.)	USPAT; US-PGPUB; 2003/06/04 EPO; JPO; 15:11 DERWENT; IBM_TDB
6	1	semiconductor and test\$3 and heat\$3 and sensor and parasitic and (buried with (heating adj element))	USPAT; US-PGPUB; 2003/06/04 EPO; JPO; 15:20 DERWENT; IBM_TDB
7	1	"10/200934"	USPAT; US-PGPUB; 2004/06/14 EPO; JPO; 12:23 DERWENT; IBM_TDB
8	6	("5195027" "5309090" "5260237").pn.	USPAT; US-PGPUB; 2004/06/14 EPO; JPO; 12:40 DERWENT; IBM_TDB
9	11693	257/467,48,797,B21,521.ccls. 73/777.ccls. 324/765-769,158,252.ccls. 374/178,183-185.ccls. D10/77.ccls. 438/18.ccls.	USPAT; US-PGPUB; 2004/06/14 EPO; JPO; 12:40 DERWENT; IBM_TDB
10	956	parasitic same temperature same substrate	USPAT; US-PGPUB; 2004/06/14 EPO; JPO; 12:41 DERWENT; IBM_TDB
11	16	(257/467,48,797,B21,521.ccls. 73/777.ccls. 324/765-769,158,252.ccls. 374/178,183-185.ccls. D10/77.ccls. 438/18.ccls.) and (parasitic same temperature same substrate)	USPAT; US-PGPUB; 2004/06/14 EPO; JPO; 14:02 DERWENT; IBM_TDB
12	5	("4356379" "5414370").pn.	USPAT; US-PGPUB; 2004/06/14 EPO; JPO; 14:02 DERWENT; IBM_TDB

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